

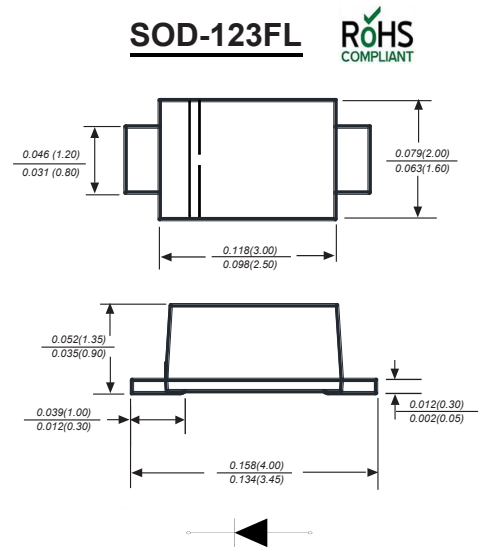
## SURFACE MOUNT SUPER FAST RECTIFIER

### Features

- ◆ Glass passivated device
- ◆ Ideal for surface mounted applications
- ◆ Low reverse leakage
- ◆ Metallurgically bonded construction
- ◆ High temperature soldering guaranteed:  
250°C/10 seconds, 0.375" (9.5mm) lead length,  
5 lbs. (2.3kg) tension

### Mechanical Data

Case: JEDEC UOD-123FL molded plastic body  
 Terminals: Solderable per MIL-STD-750, Method 2026A  
 Polarity: Polarity symbol marking on body  
 Mounting Position: Any  
 Weight: 0.0053 ounce, 0.015 grams



Dimensions in inches and (millimeters)

### Maximum Ratings And Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified.

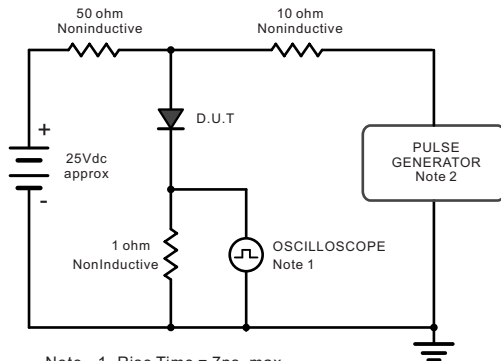
Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	SYMBOLS	DSF1A	DSF1B	DSF1C	DSF1D	DSF1E	DSF1G	DSF1J	UNITS
Marking Code		E1A	E1B	E1C	E1D	E1E	E1G	E1J	
Maximum repetitive peak reverse voltage	$V_{RRM}$	50	100	150	200	300	400	600	V
Maximum RMS voltage	$V_{RMS}$	35	70	105	140	210	280	420	V
Maximum DC blocking voltage	$V_{DC}$	50	100	150	200	300	400	600	V
Maximum average forward rectified current at TL (see fig. 1)	$I_{(AV)}$	1.0							A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	$I_{FSM}$	30							A
Maximum instantaneous forward voltage at 1.0A	$V_F$	1			1.25		1.68		V
Maximum DC reverse current $T_A=25^\circ\text{C}$ at rated DC blocking voltage $T_A=125^\circ\text{C}$	$I_R$	5 100							$\mu\text{A}$
Typical junction capacitance (NOTE 1)	$C_J$	15							pF
Maximum Reverse Recovery Time (NOTE 2)	$t_{rr}$	35							ns
Typical thermal resistance (NOTE 3)	$R_{\theta JA}$	85							$^\circ\text{C}/\text{W}$
Operating junction temperature range	$T_J$	-55 to +150							$^\circ\text{C}$
Storage temperature range	$T_{STG}$	-55 to +150							$^\circ\text{C}$

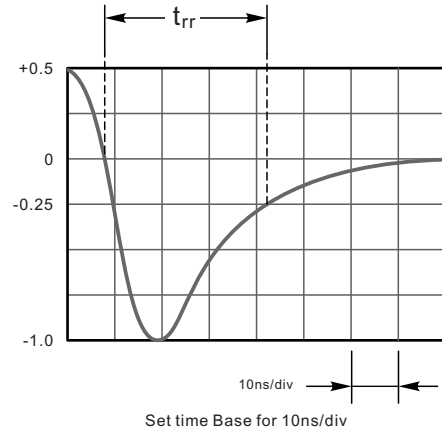
**Note:** 1. Measured with  $I_F=0.5\text{A}$ ,  $I_R=1\text{A}$ ,  $I_{rr}=0.25\text{A}$ .  
 2. Measured at 1MHz and applied reverse voltage of 4.0V D.C.  
 3. PCB mounted on 2.0\*2.0" (5.0\*5.0cm) copper pad area.

## Typical Characteristics

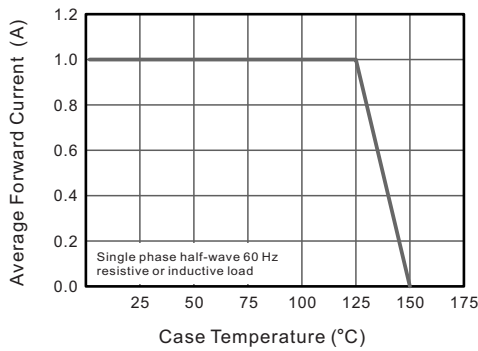
**Fig.1 Reverse Recovery Time Characteristic And Test Circuit Diagram**



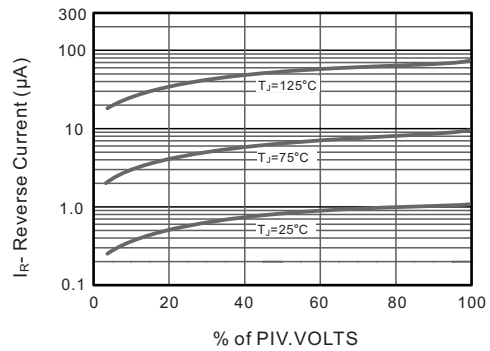
Note: 1. Rise Time = 7ns, max.  
Input Impedance = 1 megohm, 22pF.  
2. Rise Time = 10ns, max.  
Source Impedance = 50 ohms.



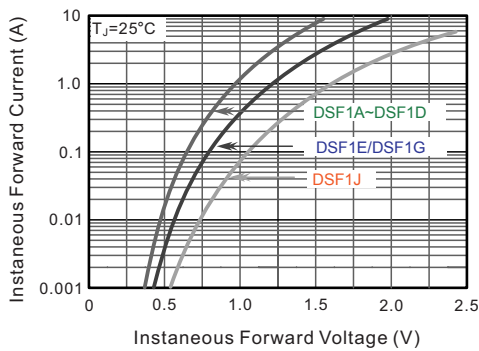
**Fig.2 Maximum Average Forward Current Rating**



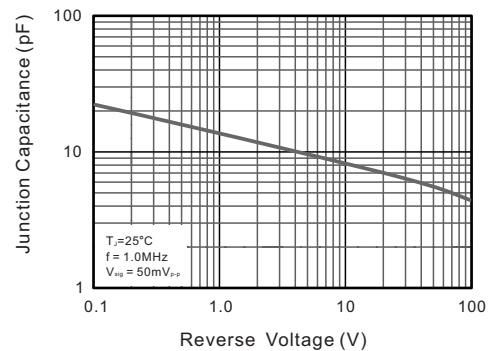
**Fig.3 Typical Reverse Characteristics**



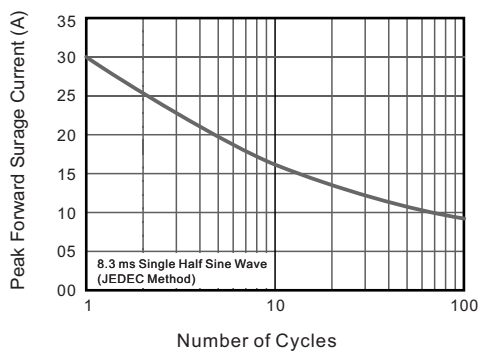
**Fig.4 Typical Forward Characteristics**



**Fig.5 Typical Junction Capacitance**

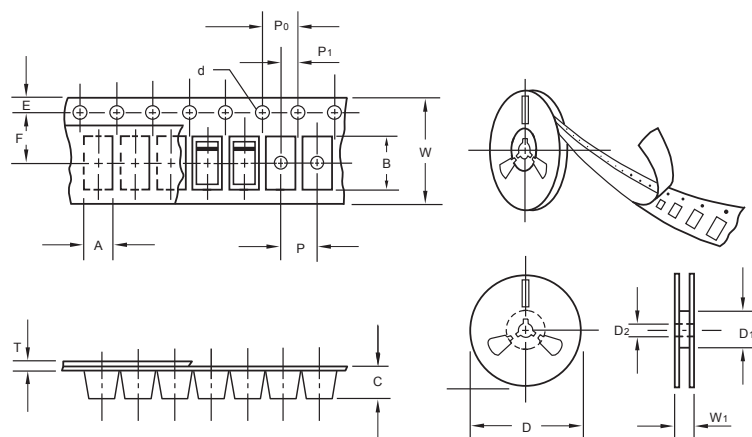


**Fig.6 Maximum Non-Repetitive Peak Forward Surge Current**



The curve above is for reference only.

## Packing information



unit:mm

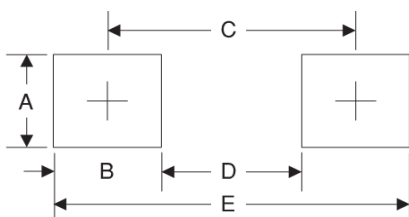
Item	Symbol	Tolerance	SOD-123FL
Carrier width	A	0.1	2.1
Carrier length	B	0.1	4.0
Carrier depth	C	0.1	1.60
Sprocket hole	d	0.05	1.55
7" Reel outside diameter	D	2.0	178.00
7" Reel inner diameter	D1	min	50.0
Feed hole diameter	D2	0.5	13.00
Sprocket hole position	E	0.1	1.75
Punch hole position	F	0.1	3.50
Punch hole pitch	P	0.1	4.00
Sprocket hole pitch	P0	0.1	4.00
Embossment center	P1	0.1	2.00
Overall tape thickness	T	0.1	0.25
Tape width	W	0.3	8.15
Reel width	W1	1.0	10.5

Note: Devices are packed in accordance with EIA standard RS-481-A and specifications listed above.

## Reel packing

PACKAGE	REEL SIZE	REEL (pcs)	COMPONENT SPACING (m/m)	BOX (pcs)	INNER BOX (m/m)	REEL DIA, (m/m)	CARTON SIZE (m/m)	CARTON (pcs)	APPROX. GROSS WEIGHT (kg)
SOD-123FL	7"	3,000	4.0	45,000	210*208*203	178	430*430*235	180,000	9.0

## Suggested Pad Layout



Symbol	Unit (mm)	Unit (inch)
A	1.2	0.047
B	1.2	0.047
C	3.2	0.126
D	2	0.079
E	4.4	0.173